

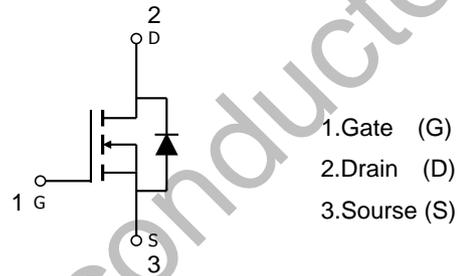
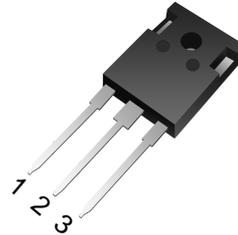


## WGA80N65W

## Features:

- Low on-resistance
- Fast switchingspeed
- Parallel use is easy
- Unrivalled Gate Charge:  $Q_g = (\text{typ}: 260\text{nC})$
- $V_{DSS} = 650\text{V}, I_D = 80\text{A}$
- $R_{DS(\text{on})} : 42\text{m}\Omega (\text{Max}) @ V_G = 10\text{V}$
- 100% Avalanche Tested

TO-247

**Absolute maximum ratings** ( $T_a = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	650	V
Continuous drain current ( $T_c = 25^\circ\text{C}$ )	$I_D^{*1}$	$\pm 80$	A
Pulsed drain current	$I_{DP}^{*2}$	$\pm 228$	A
Gate - Source voltage	$V_{GSS}$	static	$\pm 20$
		AC ( $f > 1\text{Hz}$ )	$\pm 30$
Avalanche current, single pulse	$I_{AS}$	13.4	A
Avalanche energy, single pulse	$E_{AS}^{*3}$	1954	mJ
Power dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	520	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Operating junction and storage temperature range	$T_{stg}$	-55 to +150	$^\circ\text{C}$

**Thermal resistance**

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	$R_{thJC}^{*4}$	-	-	0.25	$^\circ\text{C/W}$
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	60	$^\circ\text{C/W}$
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	265	$^\circ\text{C}$

**Electrical characteristics (T<sub>a</sub> = 25°C)**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V	-	-	100	μA
		T <sub>j</sub> = 25°C	-	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3.0	-	5.0	V
Static drain - source on - state resistance	R <sub>DS(on)</sub> <sup>*5</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A	-	0.038	0.042	Ω
		T <sub>j</sub> = 25°C	-	0.085	-	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	0.7	-	Ω

**Electrical characteristics (T<sub>a</sub> = 25°C)**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	6500	-	pF
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	4700	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	520	-	
Turn - on delay time	t <sub>d(on)</sub> <sup>*5</sup>	V <sub>DD</sub> ≈ 325V, V <sub>GS</sub> = 10V	-	65	-	ns
Rise time	t <sub>r</sub> <sup>*5</sup>	I <sub>D</sub> = 40A	-	170	-	
Turn - off delay time	t <sub>d(off)</sub> <sup>*5</sup>	R <sub>L</sub> ≈ 7.87Ω	-	450	-	
Fall time	t <sub>f</sub> <sup>*5</sup>	R <sub>G</sub> = 10Ω	-	170	-	

**Gate charge characteristics (T<sub>a</sub> = 25°C)**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q <sub>g</sub> <sup>*5</sup>	V <sub>DD</sub> ≈ 325V	-	260	-	nC
Gate - Source charge	Q <sub>gs</sub> <sup>*5</sup>	I <sub>D</sub> = 40A	-	40	-	
Gate - Drain charge	Q <sub>gd</sub> <sup>*5</sup>	V <sub>GS</sub> = 10V	-	135	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 325V, I <sub>D</sub> = 40A	-	6.0	-	V

**Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Source current	$I_S^{*1}$	$T_C = 25^\circ\text{C}$	-	-	80	A
Pulsed source current	$I_{SP}^{*2}$		-	-	240	A
Source-Drain voltage	$V_{SD}^{*5}$	$V_{GS} = 0\text{V}, I_S = 80\text{A}$	-	-	1.5	V
Reverse recovery time	$t_{rr}^{*5}$	$I_S = 80\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	990	-	ns
Reverse recovery charge	$Q_{rr}^{*5}$		-	32	-	$\mu\text{C}$
Peak reverse recovery current	$I_{rr}^{*5}$		-	65	-	A

Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

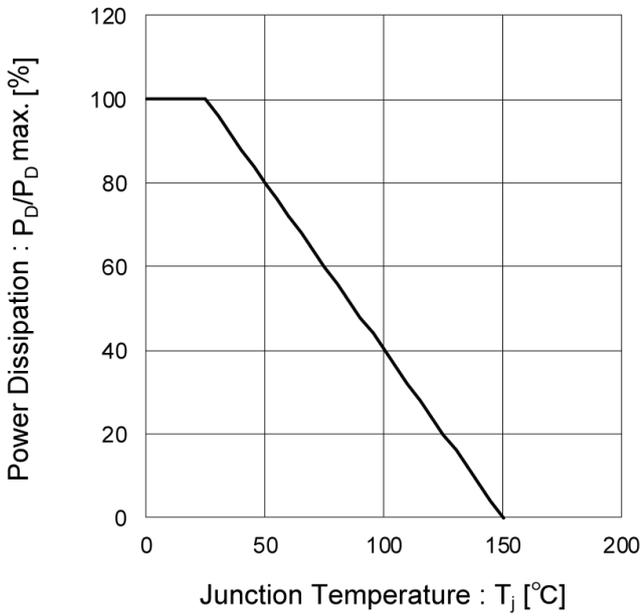


Fig.2 Drain Current Derating Curve

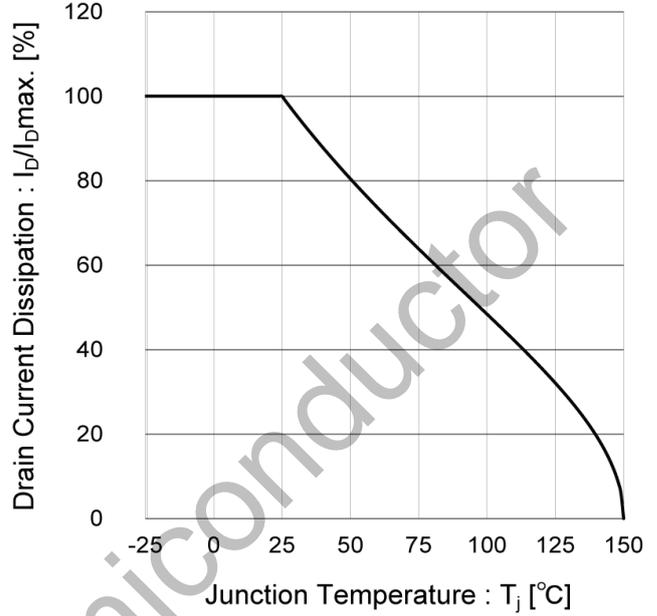


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

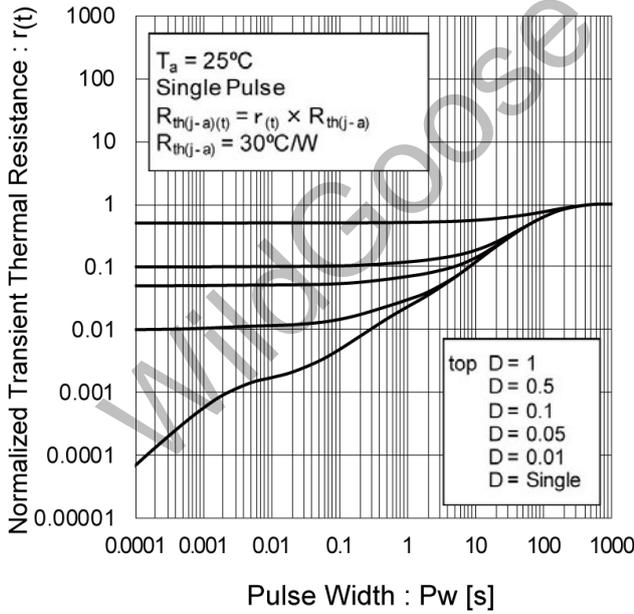
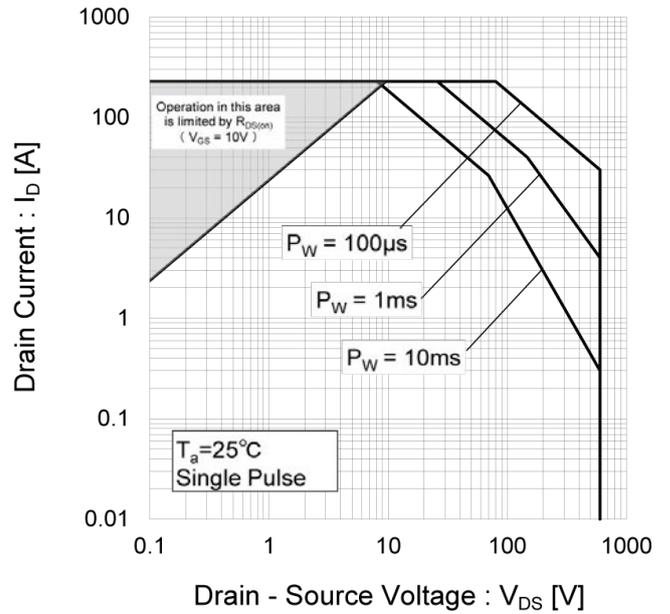


Fig.4 Maximum Safe Operating Area



Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

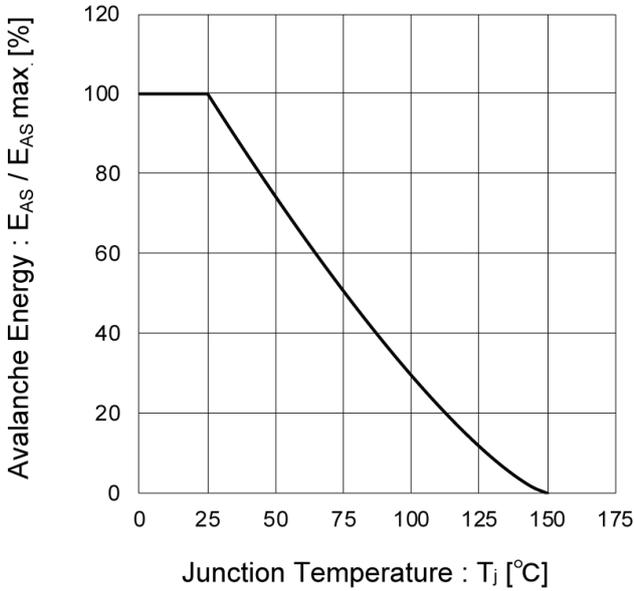


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

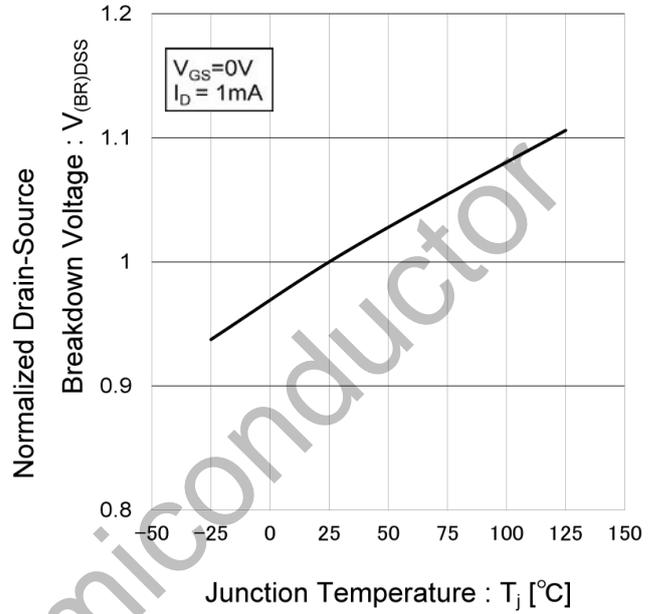


Fig.7 Typical Output Characteristics(I)

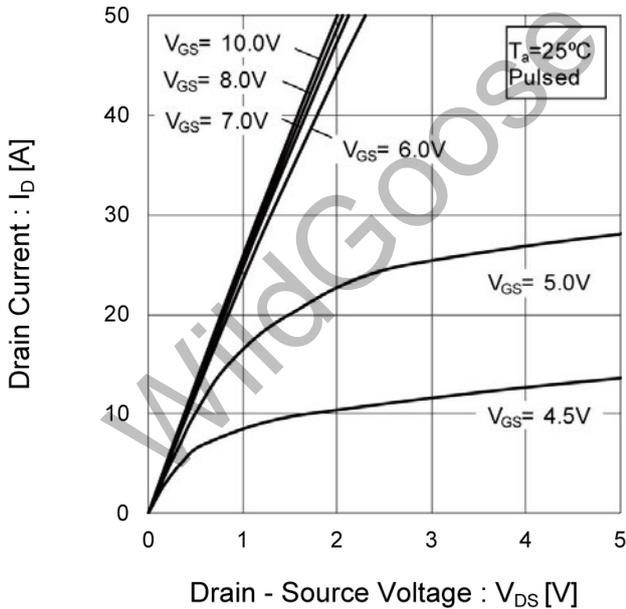
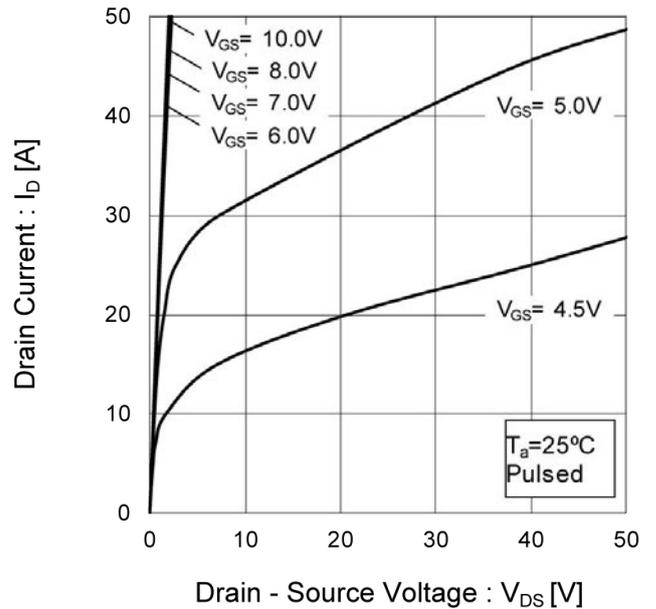


Fig.8 Typical Output Characteristics(II)



Electrical characteristic curves

Fig.9 Typical Transfer Characteristics

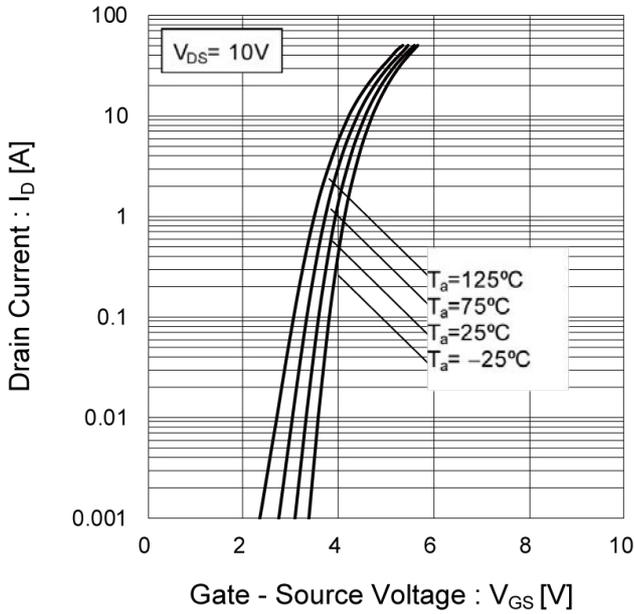


Fig.10 Gate Threshold Voltage vs. Junction Temperature

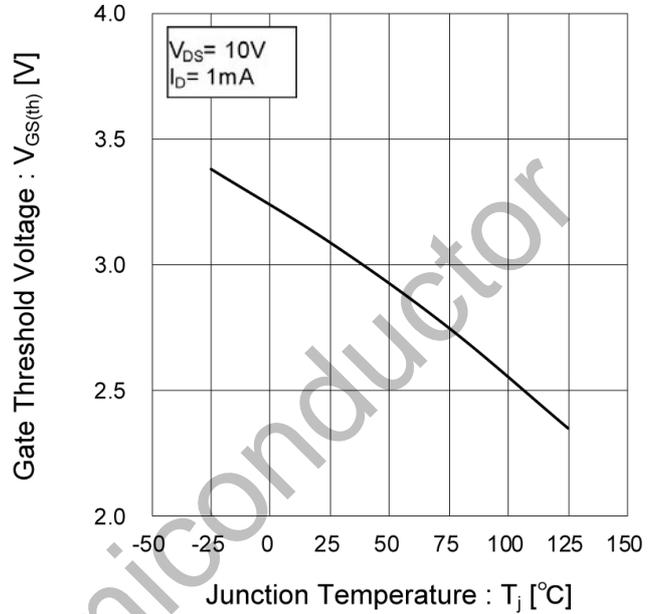


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

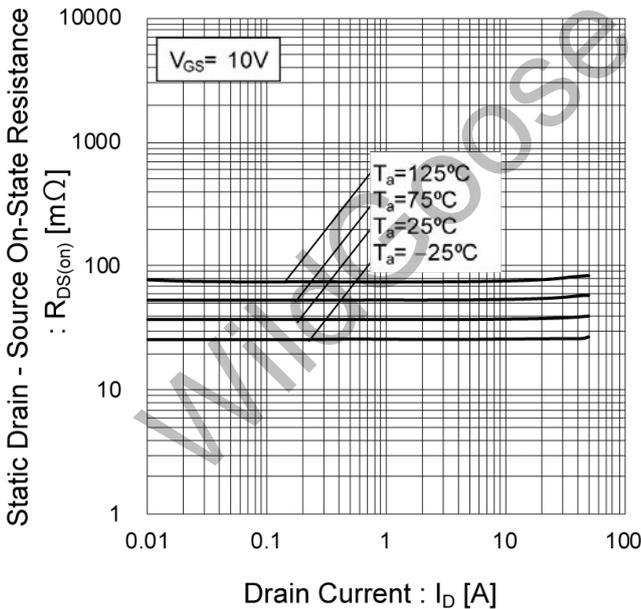
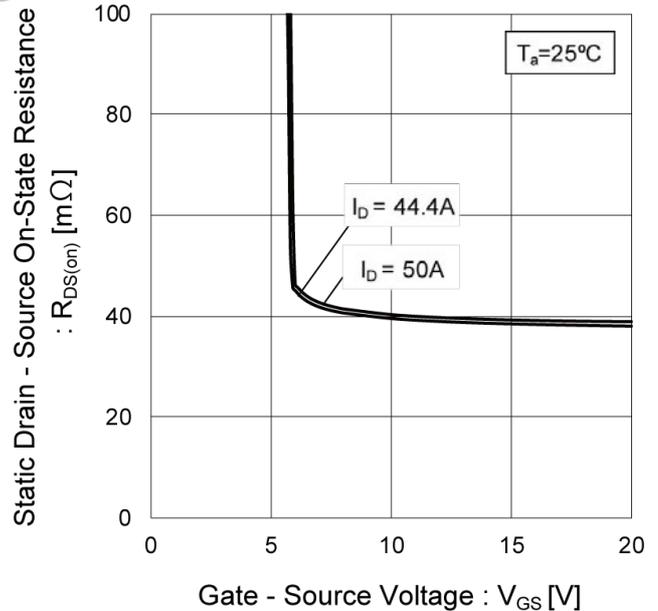


Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage



Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

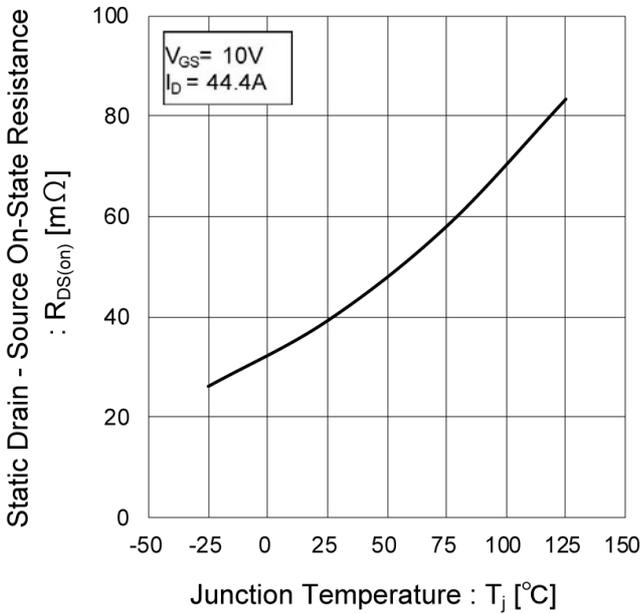


Fig.14 Typical Capacitance vs. Drain - Source Voltage

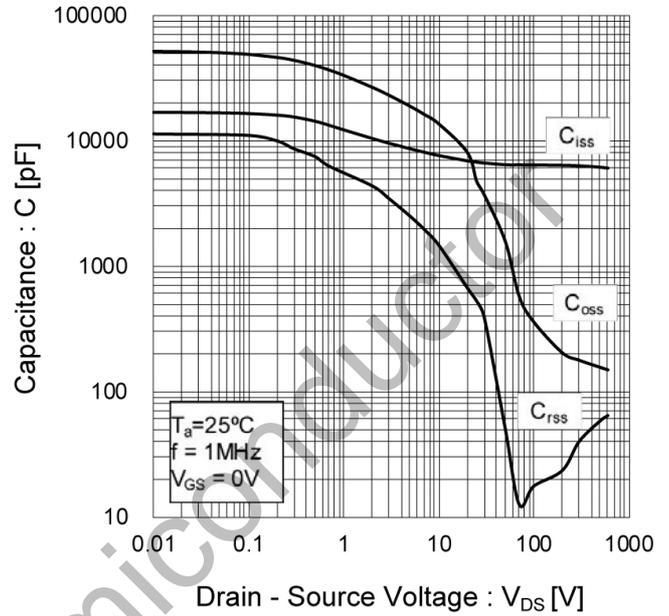


Fig.15 Switching Characteristics

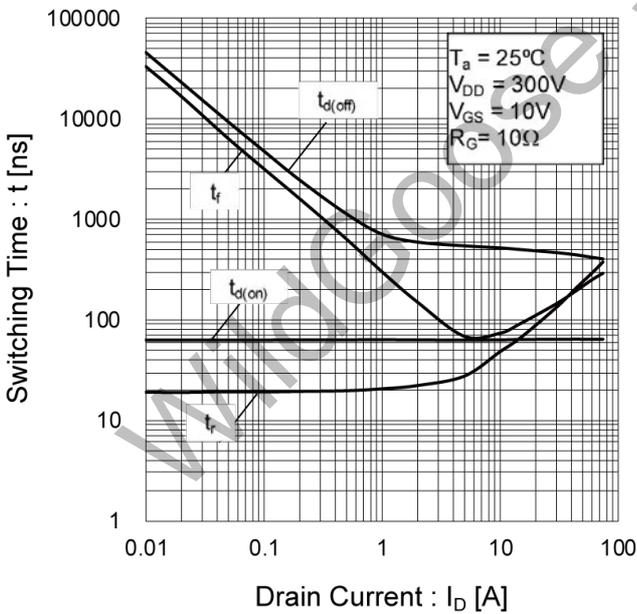
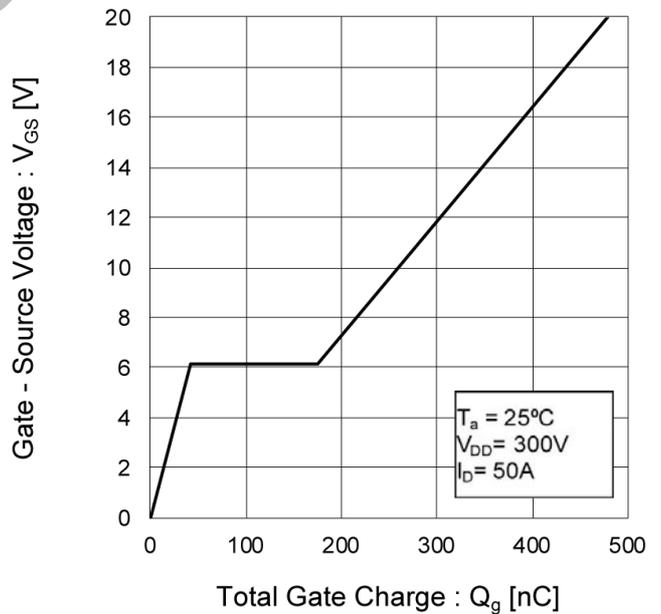


Fig.16 Typical Gate Charge



Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

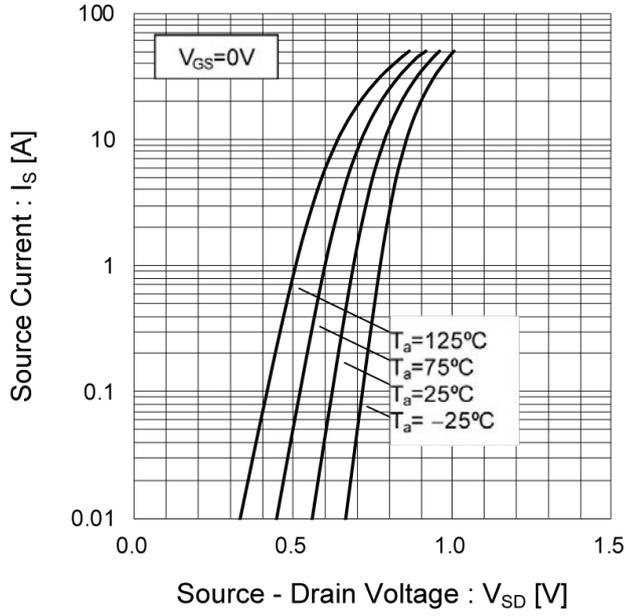
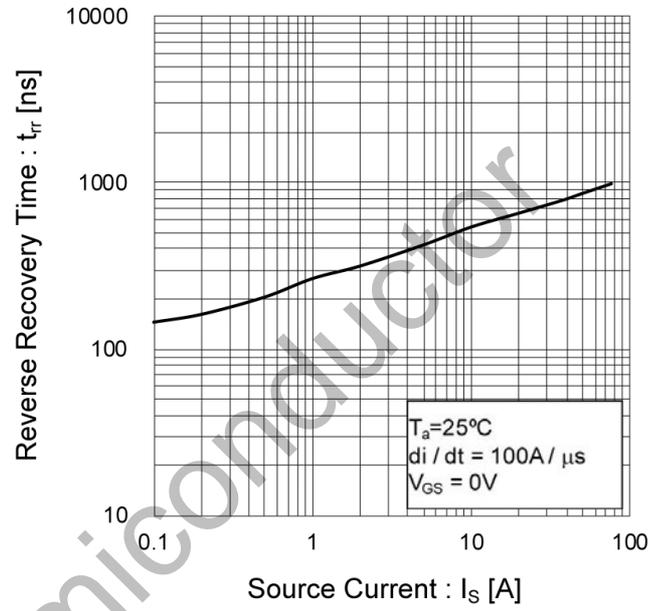


Fig.18 Reverse Recovery Time vs. Source Current



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Test Circuit and Waveform

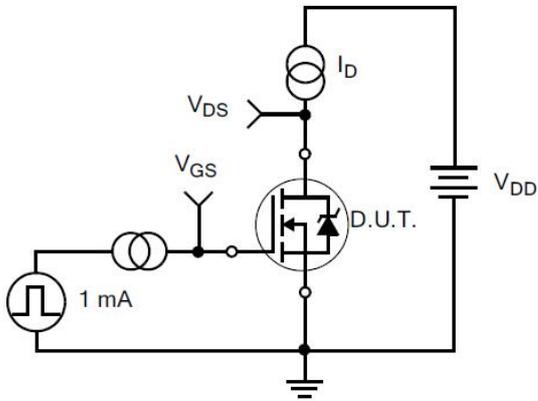


Figure 14. Gate Charge Test Circuit

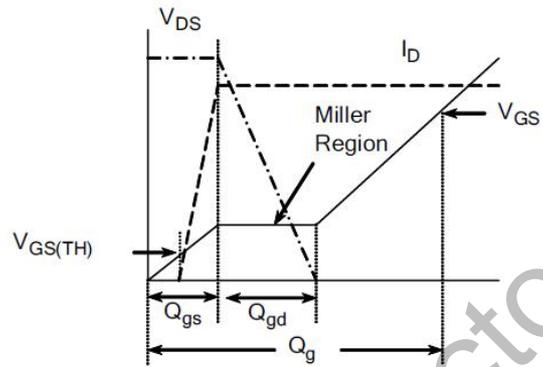


Figure 15. Gate Charge Waveforms

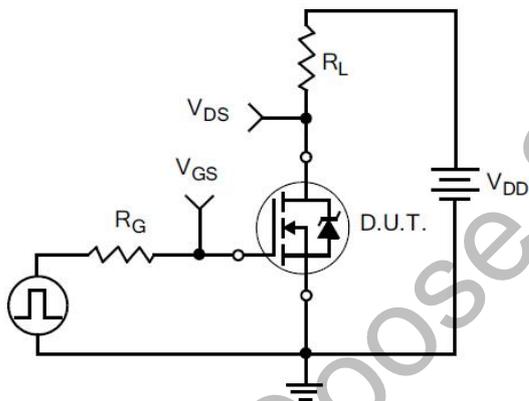


Figure 16. Resistive Switching Test Circuit

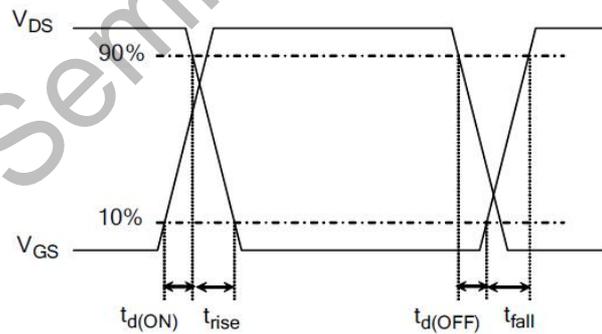


Figure 17. Resistive Switching Waveforms

Test Circuit and Waveform

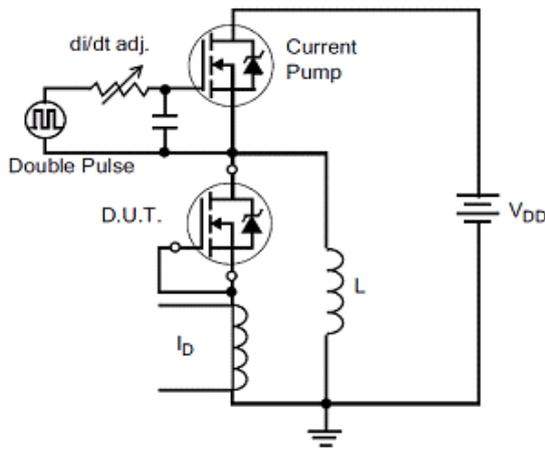


Figure 18. Diode Reverse Recovery Test Circuit

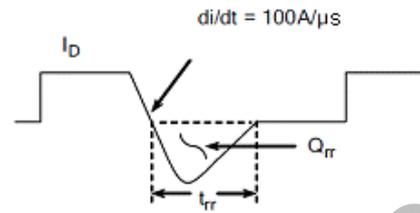


Figure 19. Diode Reverse Recovery Waveform

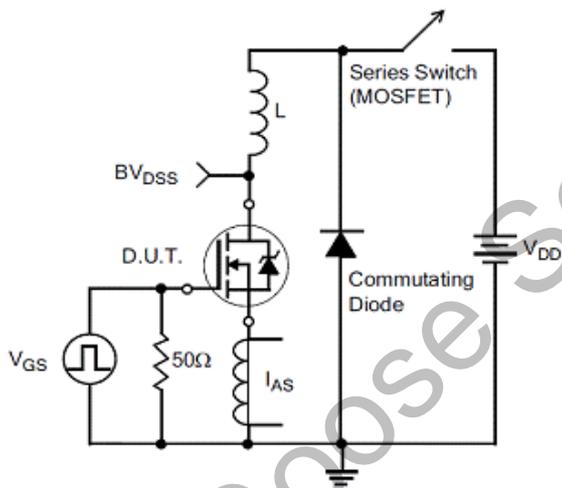


Figure 20. Unclamped Inductive Switching Test Circuit

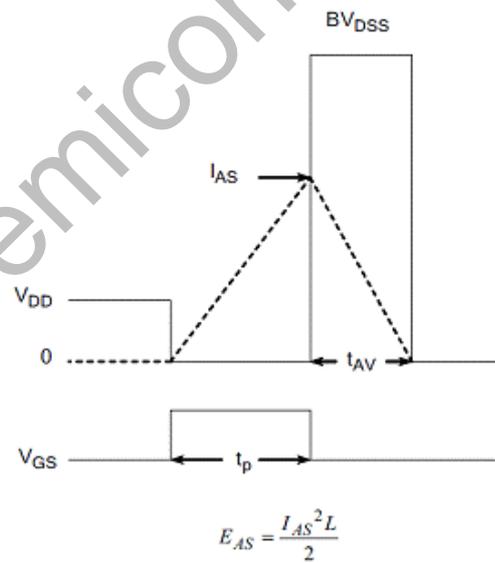
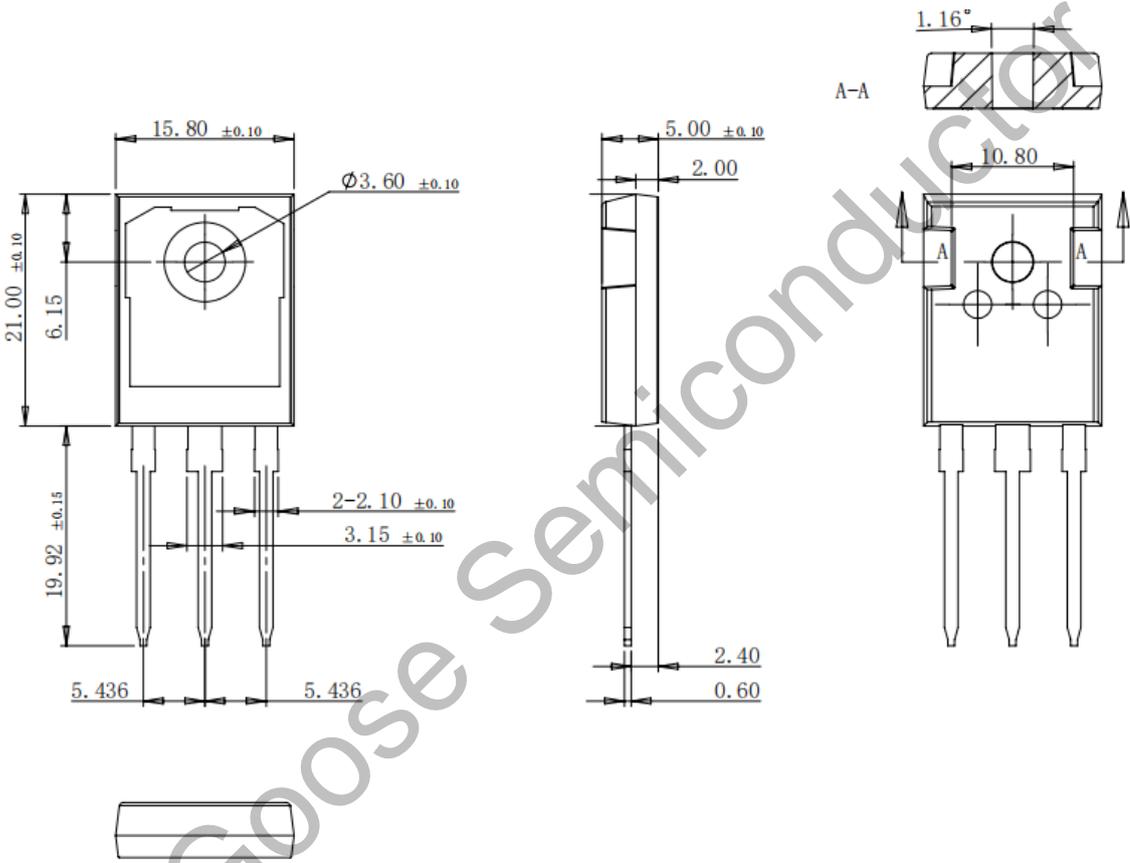


Figure 21. Unclamped Inductive Switching Waveform

**Package Dimension**

TO-247

Unit: mm



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